



# FSA2257

## Low R<sub>ON</sub>, Low-Voltage Dual SPDT Bi-Directional Analog Switch

### Features

- Maximum 1.15 Ω On Resistance (R<sub>ON</sub>) at 4.5 V V<sub>CC</sub>
- 0.3 Ω Maximum R<sub>ON</sub> Flatness at +5 V V<sub>CC</sub>
- Space-Saving MicroPak™
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.50 V
- Fast Turn-On and Turn-Off Time
- Break-Before-Make Enable Circuitry
- Over-Voltage Tolerant TTL-Compatible Control Input

### Description

The FSA2257 is a high-performance bi-directional dual Single-Pole/Double-Throw (SPDT) analog switch. This switch can be configured as either a multiplexer or a demultiplexer by select pins. The device features ultra-low R<sub>ON</sub> of 1.3 Ω maximum at 4.5 V V<sub>CC</sub> and operates over the wide V<sub>CC</sub> range of 1.65 V to 5.50 V. The device is fabricated with submicron CMOS technology to achieve fast switching speeds and is designed for break-before-make operation. The select input is TTL-level compatible.

### Applications

- Cell Phone
- PDA
- Mobile Devices

### Ordering Information

Part Number	Package Number	Top Mark	Package Description	Packing Method
FSA2257L10X	MAC10A	EP	10-Lead MicroPak™, 1.6 x 2.1 mm	5000 Units Tape and Reel
FSA2257MTCX	MCT14	FSA2257	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4 mm Wide	2500 Units Tape and Reel
FSA2257MUX	MUA10A	FSA2257	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0 mm	4000 Units Tape and Reel

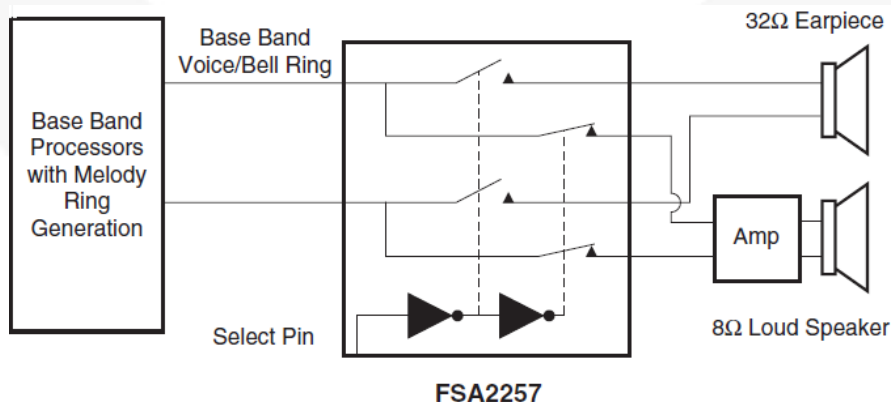


Figure 1. Block Diagram

## Pin Configurations

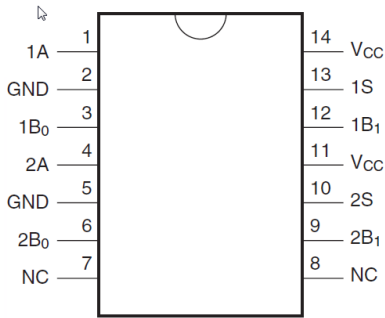


Figure 2. Pin Assignments for TSSOP (Top View)

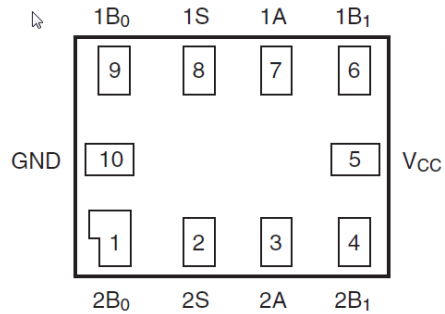


Figure 3. MicroPak™ Pad Assignments (Top View)

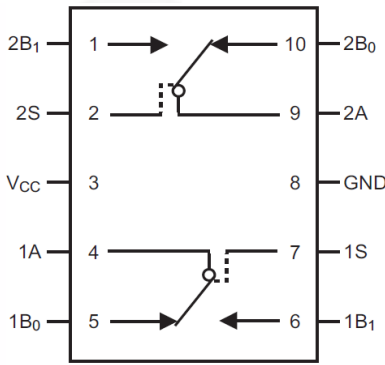


Figure 4. Pin Assignments for MSOP (Top View)

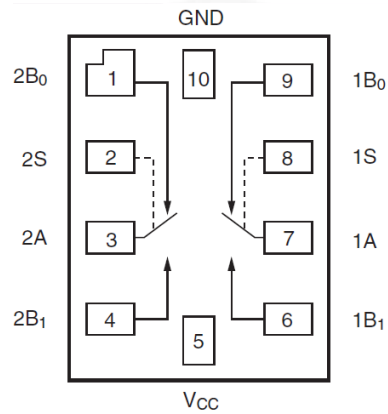


Figure 5. Analog Symbols (Top Through View)

## Pin Definitions

Pin# TSSOP	Pin# MicroPak™	Pin # MSOP	Name	Description
1	7	4	1A	Data Ports
2,5	10	8	GND	Ground
3	9	5	1B <sub>0</sub>	Data Ports
4	3	9	2A	Data Ports
6	1	10	2B <sub>0</sub>	Data Ports
7,8			NC	No Connect
9	4	1	2B <sub>1</sub>	Data Ports
10	2	2	2S	Control Inputs
11,14	5	3	V <sub>CC</sub>	Power Supply
12	6	6	1B <sub>1</sub>	Data Ports
13	8	7	1S	Control Inputs

## Truth Table

Control Input (S)	Function
Low Logic Level	B <sub>0</sub> connected to A
High Logic Level	B <sub>1</sub> connected to A

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	-0.5	6.0	V
V <sub>SW</sub>	DC Switch Voltage <sup>(1)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
V <sub>IN</sub>	DC Input Voltage <sup>(1)</sup>	-0.5	6.0	V
I <sub>IK</sub>	Input Diode Current	-50		mA
	Switch Current		200	
	Peak Switch Current (Pulsed at 1 ms duration, <10% duty cycle)		400	
T <sub>STG</sub>	Storage Temperature Range	-65	+150	°C
T <sub>J</sub>	Maximum Junction Temperature		+150	°C
T <sub>L</sub>	Lead Temperature (Soldering, 10 seconds)		+260	°C
ESD	Electrostatic Discharge Capability	Human Body Model, JESD22-A114	8000	V
		Charged Device Model, JESD22-C101	2000	

**Note:**

1. Input and output negative ratings may be exceeded if input and output diode current ratings are observed.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	1.65	5.50	V
V <sub>CNTRL</sub>	Control Input Voltage <sup>(2)</sup>	0	V <sub>CC</sub>	V
V <sub>SW</sub>	Switch Input Voltage	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

**Note:**

2. Unused control input must be held HIGH or LOW and it must not float.

## DC Electrical Characteristics

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40°C to +85°C		Unit
				Min.	Typ.	Max.	Min.	Max.	
V <sub>IH</sub>	Input Voltage High		1.8 to 2.7				1.0		V
			2.7 to 3.6				2.0		
			4.5 to 5.5				2.4		
V <sub>IL</sub>	Input Voltage Low		1.8 to 2.7					0.4	V
			2.7 to 3.6					0.6	
			4.5 to 5.5					0.8	
I <sub>IN</sub>	Control Input Leakage	V <sub>IN</sub> =0 V to V <sub>CC</sub>	2.7 to 3.6				-1.0	1.0	μA
			4.5 to 5.5				-1.0	1.0	
I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	Off Leakage Current of Port B <sub>0</sub> and B <sub>1</sub>	A=1 V, 4.5 V, B <sub>0</sub> or B <sub>1</sub> =1 V, 4.5 V	5.5	-2		2	-20	20	nA
I <sub>A(ON)</sub>	On Leakage Current of Port A	A=1 V, 4.5V, B <sub>0</sub> or B <sub>1</sub> =1 V, 4.5 V or Floating	5.5	-4		2	-40	40	nA
R <sub>ON</sub>	Switch On Resistance MicroPak <sup>(3)</sup>	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =1.5 V	1.8		4.6				Ω
			2.7		2.6	4.0		4.3	
	Switch On Resistance MSOP/TSSOP <sup>(3)</sup>	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =3.5 V	4.5		0.95	1.15		1.30	
			2.7		2.8			4.5	
ΔR <sub>ON</sub>	On Resistance Matching Between Channels MicroPak <sup>(4)</sup>	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =3.5 V	4.5		0.06	0.12		0.15	Ω
			4.5		0.7			0.3	
R <sub>FLAT(ON)</sub>	On Resistance Flatness <sup>(5)</sup>	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =0 V, 0.75 V, 1.5 V	1.8		3.0				Ω
			2.7		1.4				
		I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =0 V, 1 V, 2 V	4.5		0.2	0.3		0.4	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> =0 V or V <sub>CC</sub> , I <sub>OUT</sub> =0 V	3.6		0.1	0.5		1.0	μA
			5.5		0.1	0.5		1.0	

### Notes:

3. On resistance is determined by the voltage drop between A and B pins at the indicated current through the switch.
4. ΔR<sub>ON</sub> = R<sub>ONmax</sub> – R<sub>ONmin</sub> measured at identical V<sub>CC</sub>, temperature, and voltage.
5. Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

## AC Electrical Characteristics

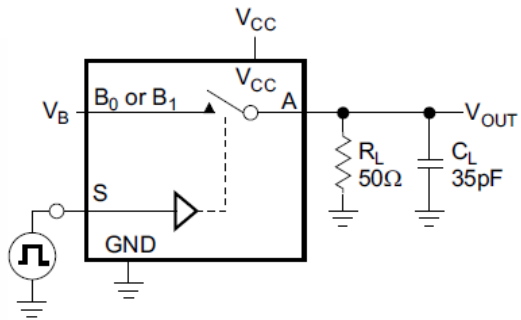
Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40°C to +85°C		Unit	Figure
				Min.	Typ.	Max.	Min.	Max.		
t <sub>ON</sub>	Turn-On Time	B <sub>0</sub> or B <sub>1</sub> =1.5 V, R <sub>L</sub> =50 Ω, C <sub>L</sub> =35 pF	1.8 to 2.7		75				ns	Figure 6
			2.7 to 3.6			50		60		
		B <sub>0</sub> or B <sub>1</sub> =3.0 V, R <sub>L</sub> =50 Ω, C <sub>L</sub> =35 pF	4.5 to 5.5			35		40		
t <sub>OFF</sub>	Turn-Off Time	B <sub>0</sub> or B <sub>1</sub> =1.5 V, R <sub>L</sub> =50 Ω, C <sub>L</sub> =35 pF	1.8 to 2.7		20			ns	Figure 6	
			2.7 to 3.6			20				30
		B <sub>0</sub> or B <sub>1</sub> =3.0 V, R <sub>L</sub> =50 Ω, C <sub>L</sub> =35 pF	4.5 to 5.5			15				20
t <sub>BBM</sub>	Break-Before-Make Time	B <sub>0</sub> or B <sub>1</sub> =1.5 V, R <sub>L</sub> =50 Ω, C <sub>L</sub> =35 pF	2.7 to 3.6				1	ns	Figure 7	
			4.5 to 5.5		20		1			
Q	Charge Injection	C <sub>L</sub> =1.0 nF, V <sub>GEN</sub> =0 V, R <sub>GEN</sub> =0 Ω	2.7 to 3.6		20			pC	Figure 9	
			4.5 to 5.5		10					
OIRR	Off Isolation	f=1 MHz, R <sub>L</sub> =50 Ω	2.7 to 3.6		-70			dB	Figure 8	
			4.5 to 5.5		-70					
Xtalk	Crosstalk	f=1 MHz, R <sub>L</sub> =50 Ω	2.7 to 3.6		-75			dB	Figure 8	
			4.5 to 5.5		-75					
BW	-3 db Bandwidth	R <sub>L</sub> =50 Ω	2.7 to 3.6		200			MHz	Figure 11	
			4.5 to 5.5		200					
THD	Total Harmonic Distortion	R <sub>L</sub> =600 Ω, V <sub>IN</sub> =0.5 V <sub>PP</sub> f=20 Hz to 20 kHz	2.7 to 3.6		0.002			%	Figure 12	
			4.5 to 5.5		0.002					

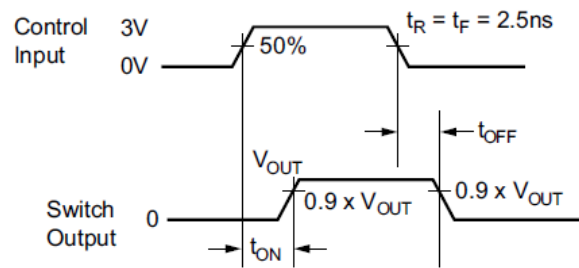
## Capacitance

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> =+25°C			Unit	Figure
				Min.	Typ.	Max.		
C <sub>IN</sub>	Control Pin Input Capacitance	f=1 MHz	0		3.5		pF	Figure 10
C <sub>OFF</sub>	B Port Off Capacitance	f=1 MHz	4.5		12.0		pF	Figure 10
C <sub>ON</sub>	A Port On Capacitance	f=1 MHz	4.5		40.0		pF	Figure 10

## AC Loadings and Waveforms

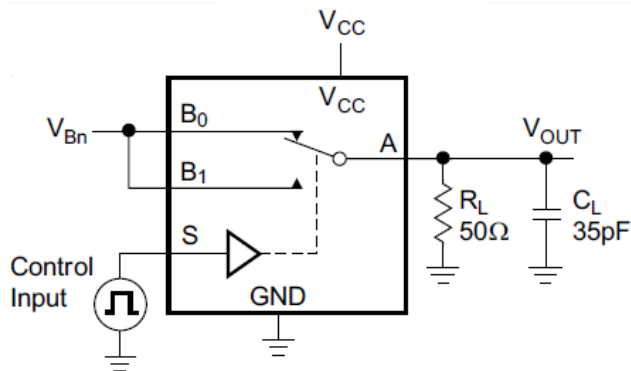


$C_L$  Includes Fixture and Stray Capacitance



Logic Input Waveforms Inverted for Switches that have the Opposite Logic Sense

Figure 6. Turn On / Off Timing



$C_L$  Includes Fixture and Stray Capacitance

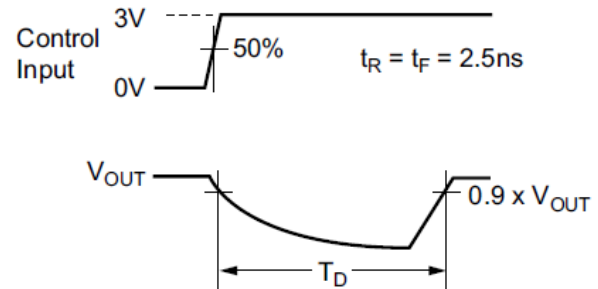


Figure 7. Break Before Make Timing

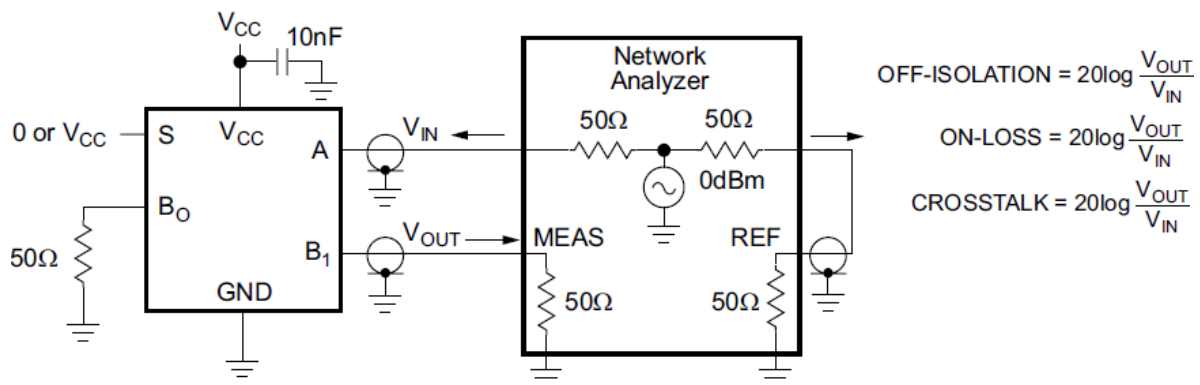


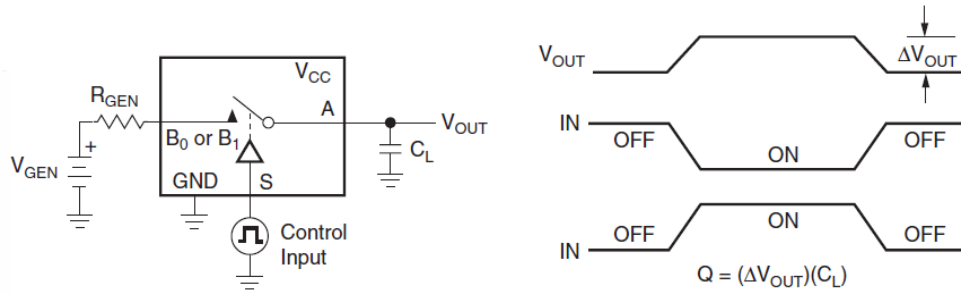
Figure 8. Off Isolation and Crosstalk

$$\text{OFF-ISOLATION} = 20 \log \frac{V_{\text{OUT}}}{V_{\text{IN}}}$$

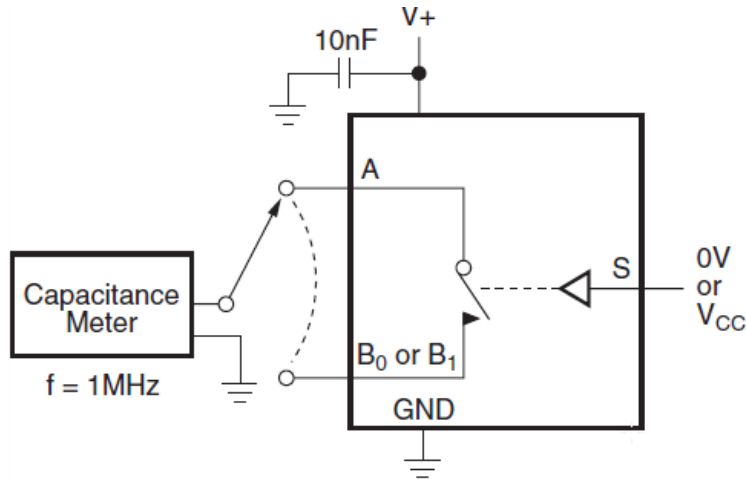
$$\text{ON-LOSS} = 20 \log \frac{V_{\text{OUT}}}{V_{\text{IN}}}$$

$$\text{CROSSTALK} = 20 \log \frac{V_{\text{OUT}}}{V_{\text{IN}}}$$

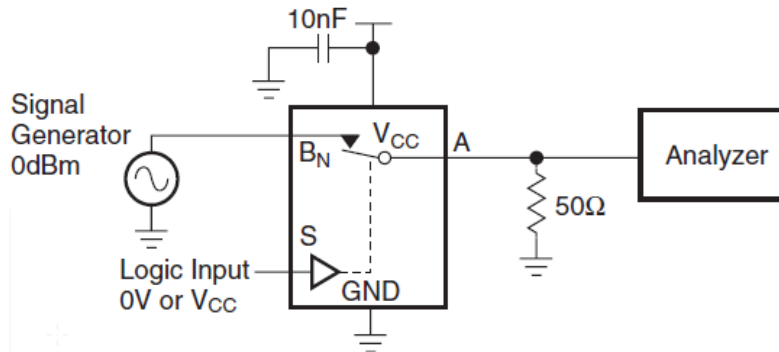
**AC Loadings and Waveforms (Continued)**



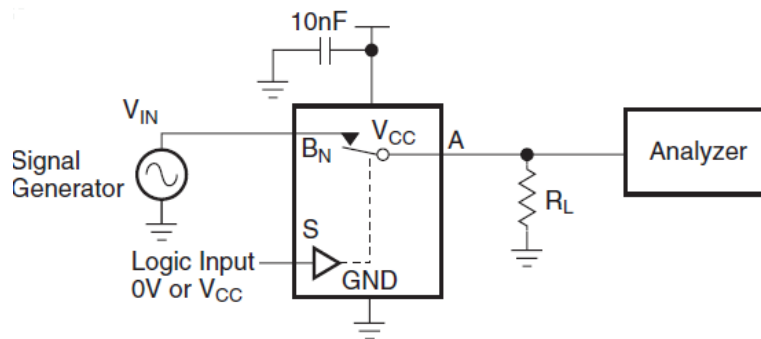
**Figure 9. Charge Injection**



**Figure 10. On / Off Capacitance Measurement Setup**



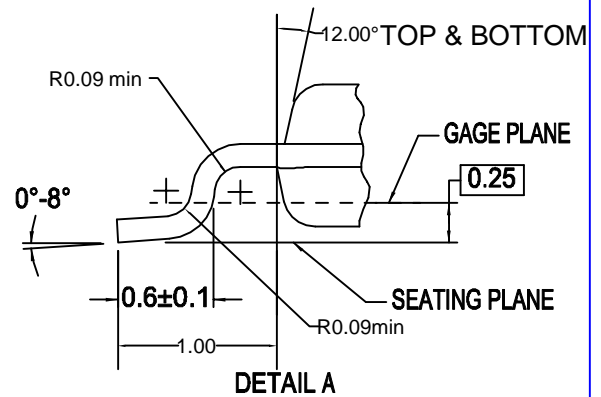
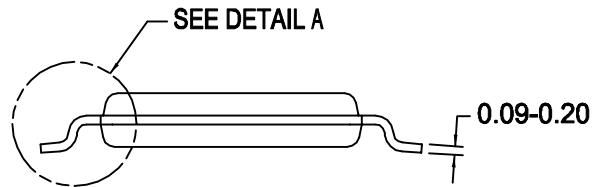
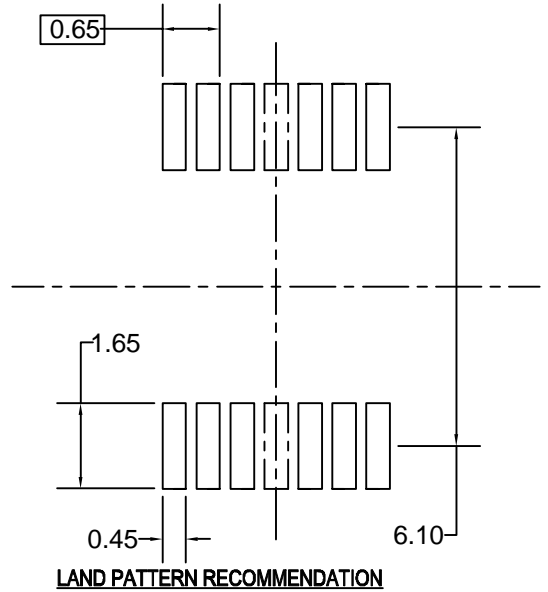
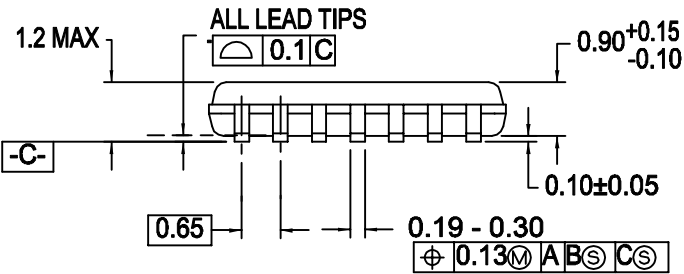
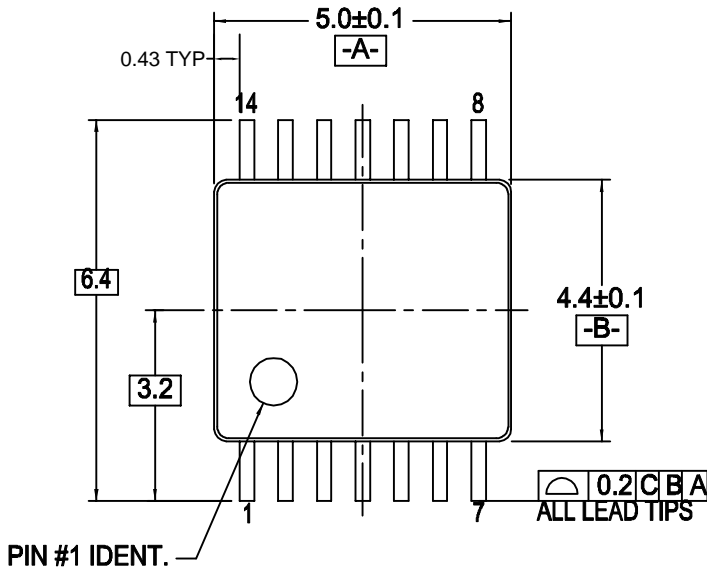
**Figure 11. Bandwidth**



**Figure 12. Harmonic Distortion**

**REVISIONS**

LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
C	REVISE & REDRAW ON PRO/E PER CURRENT STD; CORRECT DET CALLOUT FROM D TO A	11099	08/21/95	MS/
C1	CHANGE TO (FSPM) DRAWING		4-6-98	FEITAN
C2	ADDED NOTES SECTION, ADDED RADIUS DIMS, MOLDED BODY ANGLE DIMS, AND FILENAME		6-12-98	H.ALLEN
C3	CHANGED TITLE, ADDED TITLE		6-23-98	H.ALLEN
D	CHANGED REVISION LEVEL ONLY		11/12/04	H.ALLEN
6	UPDATED LAND PATTERN		9 JULY 07	L.HUEBENER



**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

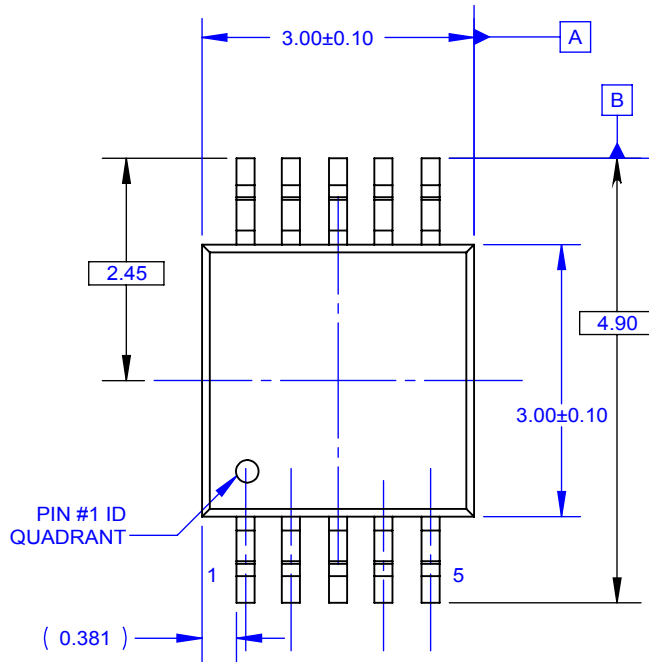
APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN L.HUEBENER	9 JULY 07	14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE		
DFTG. CHK. H.ALLEN	31 JULY 07			
ENGR. CHK.		SCALE N/A	SIZE C	DRAWING NUMBER MKT-MTC14
		DO NOT SCALE DRAWING	SHEET 1 of 1	REV 6



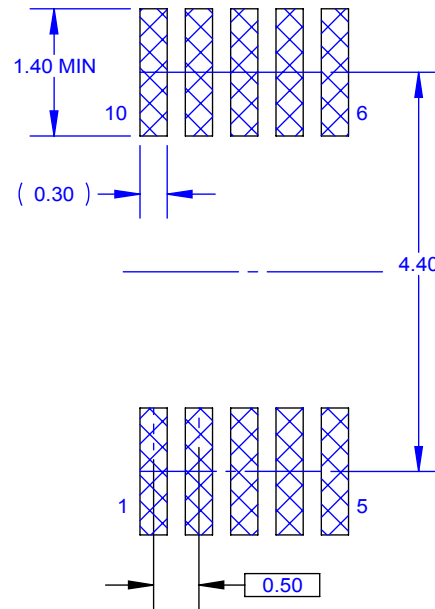
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### REVISIONS

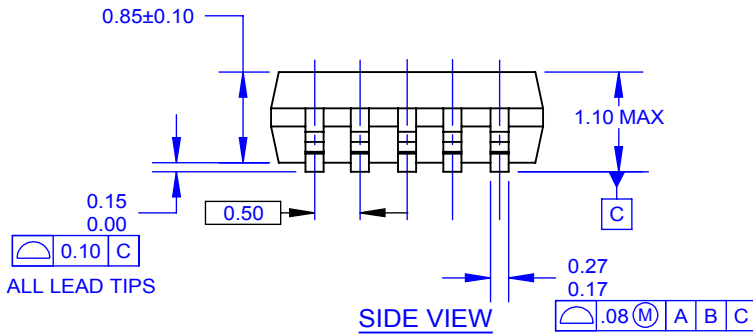
NBR	DESCRIPTION	DATE	BY/APP'D
B	REDREW FORMER NSC DWG	07JUN2006	H.ALLEN
2	* REMOVE SITE ADDRESS AND CHANGE REVISION TO NUMERICAL & CHANGED LAND PATTERN TO IPC. * CHANGE LEAD WIDTH FROM 0.27MM MAX TO 0.33MM MAX. * REMOVE DATE OF JEDEC REVISION	20AUG2009	KHLEE/FSSZ
3	* REVERT LEAD WIDTH TO 0.27MM MAX.	24SEP2009	KHLEE/FSSZ



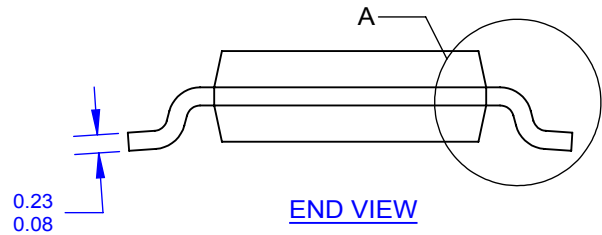
TOP VIEW



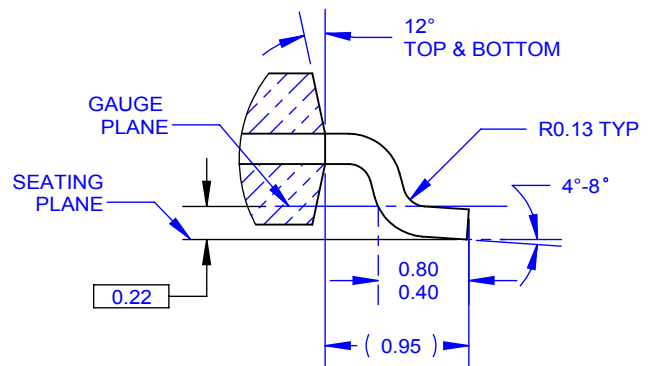
LAND PATTERN RECOMMENDATION



SIDE VIEW



END VIEW

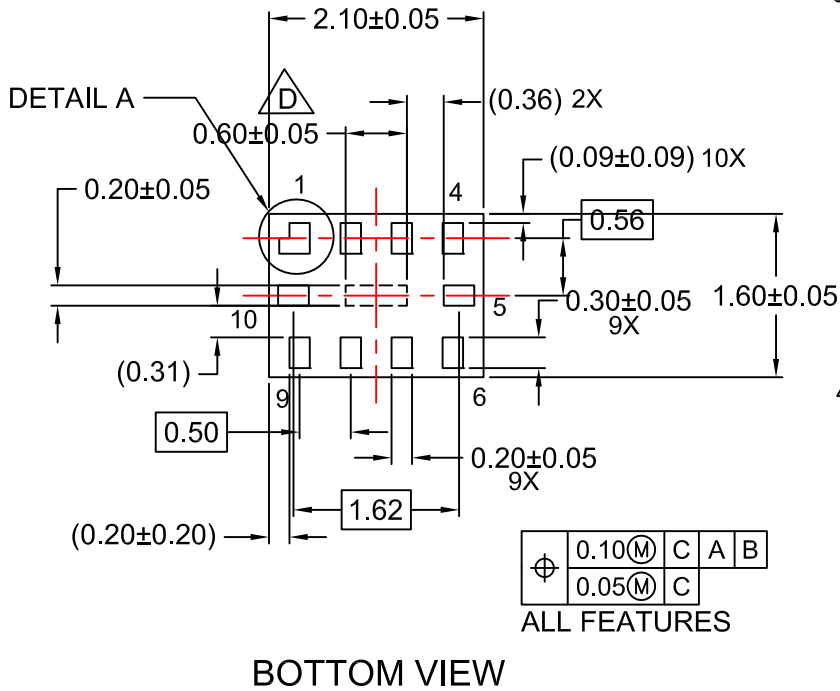
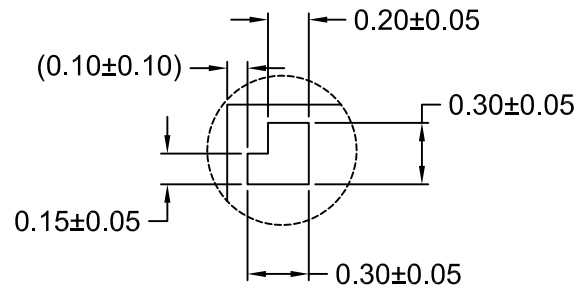
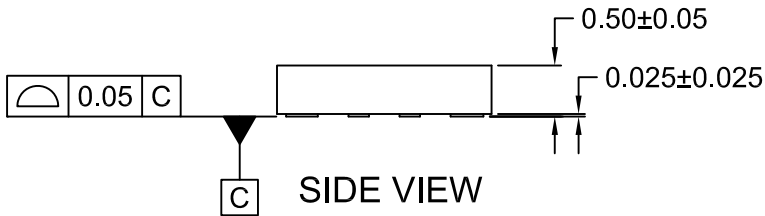
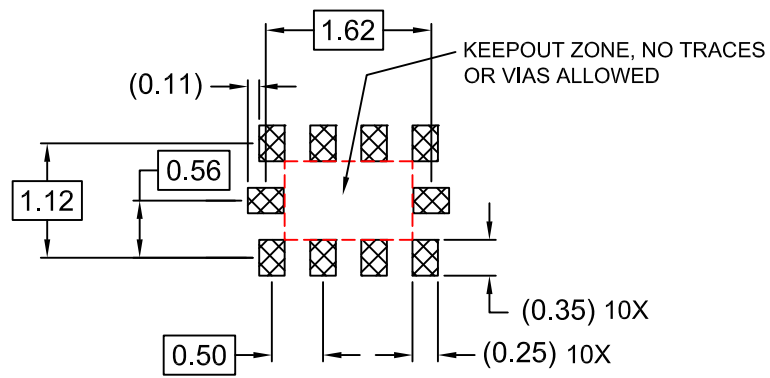
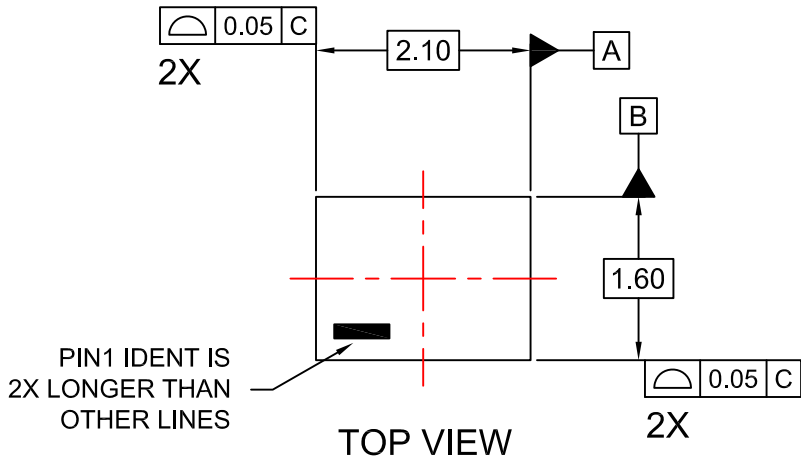


DETAIL A  
SCALE 20 : 1

NOTES: UNLESS OTHERWISE SPECIFIED

- A. THIS PACKAGE CONFORMS TO JEDEC MO-187 VARIATION BA.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
- E. LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN
- F. FILE NAME: MKT-MUA10AREV3

APPROVALS		DATE	 10LD, MSOP, JEDEC MO-187, 3.0MM WIDE			
DRAWN: BOBOY MALDO		24SEP09				
CHECKED: KH LEE						
APPROVED: BY HUANG						
APPROVED: HOWARD ALLEN			SCALE 1:1	SIZE N/A	DRAWING NUMBER MKT-MUA10A	REV 3
PROJECTION			FORMERLY: N/A		SHEET: 1 OF 1	



NOTES:

- A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD .
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.
- E. DRAWING FILENAME: MKT-MAC10Arev6.
- F. DIMENSIONS WITHIN ( ) ARE UNCONTROLLED





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AX-CAP®*	GreenBridge™	PowerXS™	TinyCalc™
BitSiC™	Green FPS™	Programmable Active Droop™	TinyLogic®
Build it Now™	Green FPS™ e-Series™	QFET®	TINYOPTO™
CorePLUS™	Gmax™	QS™	TinyPower™
CorePOWER™	GTO™	Quiet Series™	TinyPWM™
CROSSVOLT™	IntelliMAX™	RapidConfigure™	TinyWire™
CTL™	ISOPLANAR™		TranSiC™
Current Transfer Logic™	Making Small Speakers Sound Louder and Better™	Saving our world, 1mW/W/kW at a time™	TriFault Detect™
DEUXPEED®	MegaBuck™	SignalWise™	TRUECURRENT®*
Dual Cool™	MICROCOUPLER™	SmartMax™	μSerDes™
EcoSPARK®	MicroFET™	SMART START™	
EfficientMax™	MicroPak™	Solutions for Your Success™	UHC®
ESBC™	MicroPak2™	SPM®	Ultra FRFET™
	MillerDrive™	STEALTH™	UniFET™
Fairchild®	MotionMax™	SuperFET®	VCX™
Fairchild Semiconductor®	MotionGrid®	SuperSOT™-3	VisualMax™
FACT Quiet Series™	MTI®	SuperSOT™-6	VoltagePlus™
FACT®	MTX®	SuperSOT™-8	XS™
FAST®	MVN®	SupreMOS®	Xsens™
FastvCore™	mWSaver®	SyncFET™	仙童™
FETBench™	OptoHiT™	Sync-Lock™	
FPS™	OPTOLOGIC®		

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As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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### PRODUCT STATUS DEFINITIONS

#### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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